

Eat Well, Live Well.

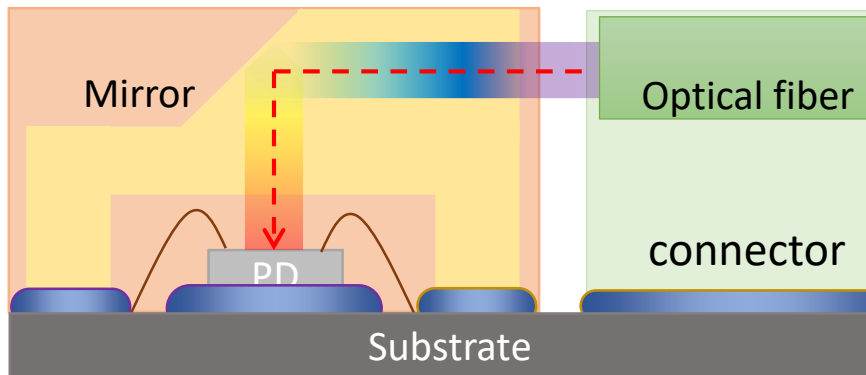
One Component Epoxy Adhesive

Innovation Provider



# PLENSET™

## Adhesive for Photodiode (PD)-integrated optical transceiver module



 :Adhesives

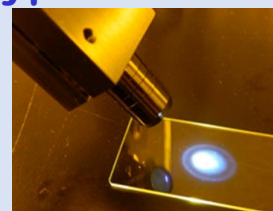
### Low modulus type

- Flexibility / low stress
- High peel strength
- Curable at 80degC



### UV fixing type

- Temporary fixing by UV
- Curable at 80degC to UV unirradiated area



### Conductive type

- Electrically & thermally conductive
- Curable at 80degC



### Transparent type

- Curable at 80degC or UV curable type
- High optical transparency
- **90% at 100um (350nm) Refractive index 1.55**
- Excel resistance of UV passivation

Item			UV fixing type	Electrically Conductive type	Thermal conductive type	High reliability	Transparent type
			DC-411	CJ series	FT series	TR-69	LT-001
Before curing	Appearance		Black	Silver	Black	Black	Colorless
	Viscosity 5rpm (Pa·s)		6	27 - 80	24 - 50	30	47
	Thixotropic Index		1.3	3.2 - 5.5	2.6	1.3	1.0
Curing temp.			UV+80degC	80degC	80degC	140degC	80degC
After curing	Lap shear strength (N/mm <sup>2</sup> )	Ni plated	7	10	10 - 21	14	-
	Flexural modulus(GPa)		0.03	1.5	0.1	3.4	2.5
	Glass transition temperature(°C)		25	88	17	105	75
	Thermal conductivity(W/mK)		-	1.2 - 1.8	1.3 - 2.0	-	-

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PLENSET™ is a series of one-component epoxy resin adhesives based on latent curing agent technologies which have been successively developed by Ajinomoto Fine-Techno. It plays active roles in various fields, such as precision electronic components including camera modules, semiconductor packaging, and car electronics.

## Effects and Features

- ✓ **One-component**
- ✓ **Low Temperature-Curability, Rapid Curing**
- ✓ **Long Pot-life**

PLENSET™ can bond heat-sensitive materials (plastics, lenses etc.) and components.

PLENSET™ can cure in a very short time at medium temperature (around 150degC) to an increase in efficiency of production.

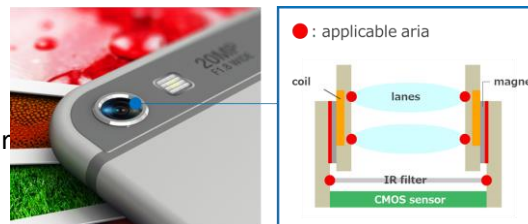


Fig. Application of PLENSET for compact camera module

## Applications

Precision Electric Components for Mobile phone, PC, Car electronics etc.

## Product line-up and Properties

- ◆ **Low Temperature Curing Type : AE-901 series**  
Cures at the low temperature of 60degC in the short time of 30min
- ◆ **Flexible Type : AE-400 series**  
Reduces stress under curing, absorb mechanical impact, vibration and the like
- ◆ **Impregnation Type : AE-700 series**  
Cures in narrow gap
- ◆ **Electrically Conductive Type : CJ series**  
Cures at 80degC, unequaled by any other one-component epoxy electrically conductive adhesive
- ◆ **Gas barrier Type : AES series**  
Protection from moisture and other gases permeation
- ◆ **UV / thermal dual cure Type : DC series**  
Temporary fixing of precision component by UV curing.  
Non-UV irradiated areas adhesion by thermal cure

※ Some varieties of PLENSET™ are not listed on TSCA, please consult to us in advance.